ABSTRACT OF THE DISCLOSURE

INTEGRATED CIRCUIT SUBSTRATE HAVING LASER-EXPOSED TERMINALS

An integrated circuit substrate having laser-exposed terminals provides a high-density and low cost mounting and interconnect structure for integrated circuits. The laser-exposed terminals can further provide a selective plating feature by using a dielectric layer of the substrate to prevent plating terminal conductors and subsequently exposing the terminals via laser ablation. A metal layer may be coated on one or both sides with a dielectric material, conductive material embedded within the dielectric to form conductive interconnects and then coating over the conductive material with a conformal protective coating. The protectant is then laser-ablated to expose the terminals. A dielectric film having a metal layer laminated on one side may be etched and plated. Terminals are then laser-exposed from the back side of the metal layer exposing unplated terminals.